

# SOT978-1

plastic low profile fine-pitch ball grid array package; 276 balls; body 15 x 15 x 1 mm

8 February 2016

Package information

## 1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA276
Package type industry code	LFBGA276
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	10-11-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.9	-	15	15.1	mm
E	package width		14.9	-	15	15.1	mm
A	seated height		[tbd]	-	[tbd]	1.5	mm
A <sub>2</sub>	package height		0.95	-	1	1.1	mm
n <sub>2</sub>	actual quantity of termination		-	-	276	-	



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2. Package outline

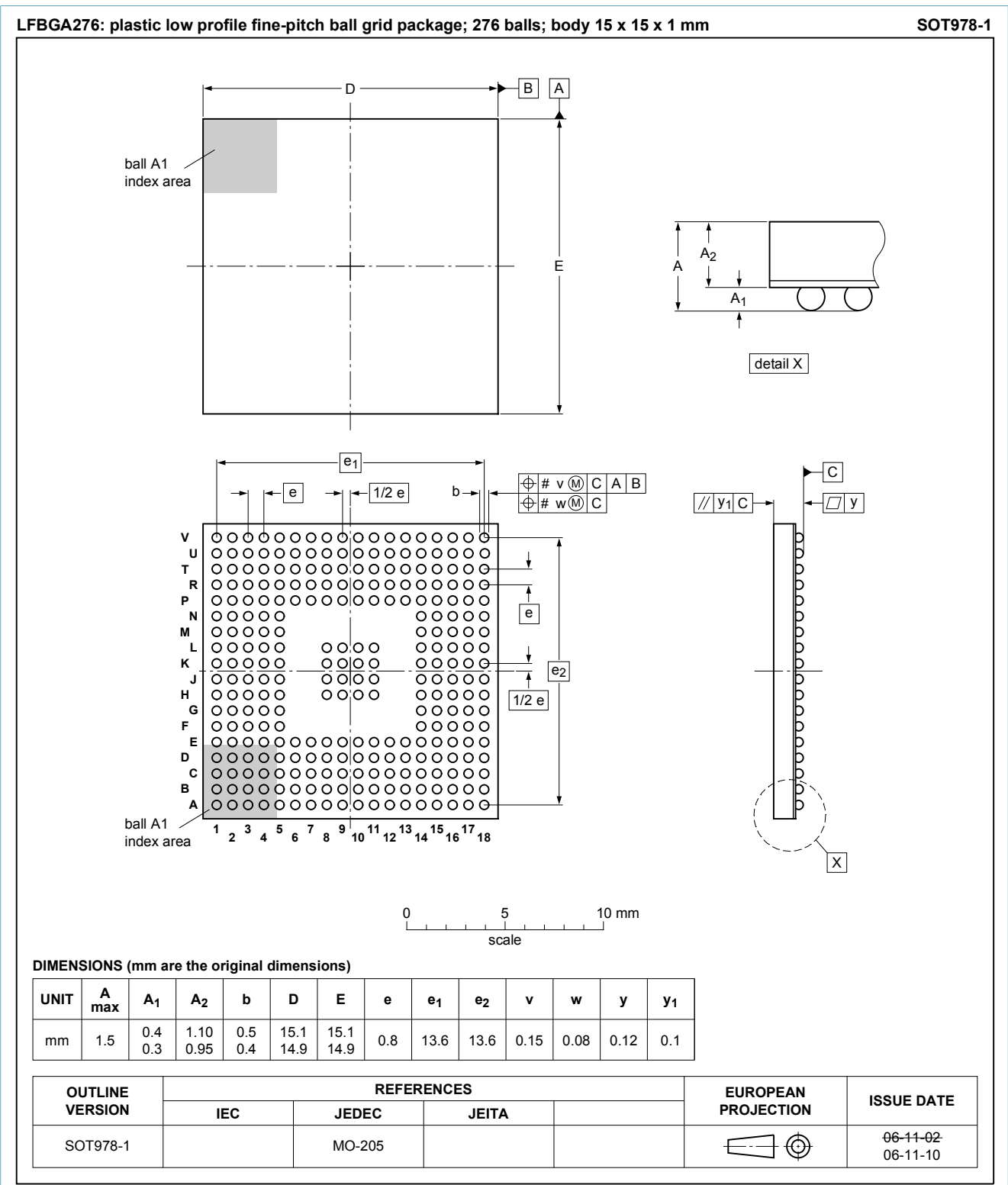


Fig. 1. Package outline LFBGA276 (SOT978-1)

### 3. Legal information

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